



Reference Specification

Leaded MLCC for General Purpose
RDE Series

Product specifications in this catalog are as of Aug. 2023, and are subject to change or obsolescence without notice.

Please consult the approval sheet before ordering. Please read rating and Cautions first.

⚠ CAUTION

1. OPERATING VOLTAGE

When DC-rated capacitors are to be used in AC or ripple current circuits, be sure to maintain the V_{p-p} value of the applied voltage or the V_{o-p} which contains DC bias within the rated voltage range. When the voltage is started to apply to the circuit or it is stopped applying, the irregular voltage may be generated for a transit period because of resonance or switching. Be sure to use a capacitor within rated voltage containing these irregular voltage.

When DC-rated capacitors are to be used in input circuits from commercial power source (AC filter), be sure to use Safety Recognized Capacitors because various regulations on withstand voltage or impulse withstand established for each equipment should be taken into considerations.

Voltage	DC Voltage	DC+AC Voltage	AC Voltage	Pulse Voltage(1)	Pulse Voltage(2)
Positional Measurement					

2. OPERATING TEMPERATURE AND SELF-GENERATED HEAT

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range. Be sure to take into account the heat generated by the capacitor itself.

When the capacitor is used in a high-frequency current, pulse current or the like, it may have the self-generated heat due to dielectric-loss. In case of Class 2 capacitors (Temp.Char. : X7R,X7S,X8L, etc.), applied voltage should be the load such as self-generated heat is within 20 °C on the condition of atmosphere temperature 25 °C. Please contact us if self-generated heat is occurred with Class 1 capacitors (Temp.Char. : C0G,U2J,X8G, etc.). When measuring, use a thermocouple of small thermal capacity-K of Φ0.1mm and be in the condition where capacitor is not affected by radiant heat of other components and wind of surroundings. Excessive heat may lead to deterioration of the capacitor's characteristics and reliability.

3. FAIL-SAFE

Be sure to provide an appropriate fail-safe function on your product to prevent a second damage that may be caused by the abnormal function or the failure of our product.

4. OPERATING AND STORAGE ENVIRONMENT

The insulating coating of capacitors does not form a perfect seal; therefore, do not use or store capacitors in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. And avoid exposure to moisture. Before cleaning, bonding, or molding this product, verify that these processes do not affect product quality by testing the performance of a cleaned, bonded or molded product in the intended equipment. Store the capacitors where the temperature and relative humidity do not exceed 5 to 40 °C and 20 to 70%. Use capacitors within 6 months.

5. VIBRATION AND IMPACT

Do not expose a capacitor or its leads to excessive shock or vibration during use.

6. SOLDERING

When soldering this product to a PCB/PWB, do not exceed the solder heat resistance specification of the capacitor. Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can crack the ceramic element.

7. BONDING AND RESIN MOLDING, RESIN COAT

In case of bonding, molding or coating this product, verify that these processes do not affect the quality of capacitor by testing the performance of a bonded or molded product in the intended equipment.

In case of the amount of applications, dryness / hardening conditions of adhesives and molding resins containing organic solvents (ethyl acetate, methyl ethyl ketone, toluene, etc.) are unsuitable, the outer coating resin of a capacitor is damaged by the organic solvents and it may result, worst case, in a short circuit.

The variation in thickness of adhesive or molding resin may cause a outer coating resin cracking and/or ceramic element cracking of a capacitor in a temperature cycling.

8. TREATMENT AFTER BONDING AND RESIN MOLDING, RESIN COAT

When the outer coating is hot (over 100 °C) after soldering, it becomes soft and fragile.

So please be careful not to give it mechanical stress.

Failure to follow the above cautions may result, worst case, in a short circuit and cause fuming or partial dispersion when the product is used.

9. LIMITATION OF APPLICATIONS

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property.

- | | |
|--|---|
| 1. Aircraft equipment | 2. Aerospace equipment |
| 3. Undersea equipment | 4. Power plant control equipment |
| 5. Medical equipment | 6. Transportation equipment (vehicles, trains, ships, etc.) |
| 7. Traffic signal equipment | 8. Disaster prevention / crime prevention equipment |
| 9. Data-processing equipment exerting influence on public | |
| 10. Application of similar complexity and/or reliability requirements to the applications listed in the above. | |

NOTICE

1. CLEANING (ULTRASONIC CLEANING)

To perform ultrasonic cleaning, observe the following conditions.

Rinse bath capacity : Output of 20 watts per liter or less.

Rinsing time : 5 min maximum.

Do not vibrate the PCB/PWB directly.

Excessive ultrasonic cleaning may lead to fatigue destruction of the lead wires.

2. SOLDERING AND MOUNTING

Insertion of the Lead Wire

- When soldering, insert the lead wire into the PCB without mechanically stressing the lead wire.
- Insert the lead wire into the PCB with a distance appropriate to the lead space.

3. CAPACITANCE CHANGE OF CAPACITORS

• Class 2 capacitors (Temp.Char. : X7R,X7S,X8L etc.)

Class 2 capacitors have an aging characteristic, whereby the capacitor continually decreases its capacitance slightly if the capacitor leaves for a long time. Moreover, capacitance might change greatly depending on a surrounding temperature or an applied voltage. So, it is not likely to be able to use for the time constant circuit.

Please contact us if you need a detailed information.

NOTE

1. Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
2. You are requested not to use our product deviating from this specification.

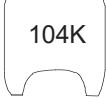
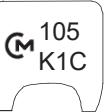
- Package

Code	Package
A	Taping type of Ammo
B	Bulk type

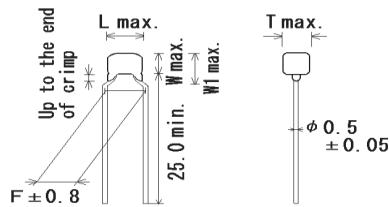
3. Marking

- Temp. char. : Letter code : C (X7R/X7S Char. Except dimension code : 0,1)
 Capacitance : 3 digit numbers
 Capacitance tolerance : Code
 Rated voltage : Letter code : 2 (DC25V. Except dimension code : 0,1)
 Letter code : 5 (DC50V. Except dimension code : 0,1)
 Letter code : 1 (DC100V. Except dimension code : 0,1)
 Company name code : Abbreviation :  (Except dimension code : 0,1)

(Ex.)

Rated voltage Dimension code	DC25V	DC50V	DC100V
0,1			
2			
3,W			

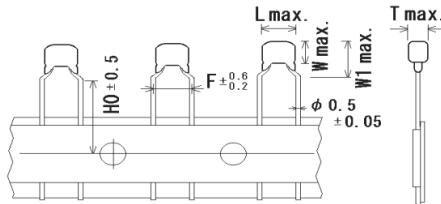
- Inside Crimp
(Lead Style : K*)



Unit : mm

Customer Part Number	Murata Part Number	T.C.	DC Rated Volt. (V)	Cap.	Cap. Tol.	Dimension (mm)					Dimension (LxW) Lead Style	Pack qty. (pcs)
						L	W	W1	F	T		
	RDER72A334K1K1H03B	X7R	100	0.33µF	±10%	4.5	3.5	5.0	5.0	3.15	1K1	500
	RDER72A474K1K1H03B	X7R	100	0.47µF	±10%	4.5	3.5	5.0	5.0	3.15	1K1	500
	RDER72A684K2K1H03B	X7R	100	0.68µF	±10%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RDER72A105K2K1H03B	X7R	100	1.0µF	±10%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RDEC72A155K3K1H03B	X7S	100	1.5µF	±10%	5.5	5.0	7.5	5.0	4.0	3K1	500
	RDEC72A225K3K1H03B	X7S	100	2.2µF	±10%	5.5	5.0	7.5	5.0	4.0	3K1	500
	RDEC72A475K3K1H03B	X7S	100	4.7µF	±10%	5.5	5.0	7.5	5.0	4.0	3K1	500
	RDEC72A475MWK1H03B	X7S	100	4.7µF	±20%	5.5	7.5	10.0	5.0	4.0	WK1	500

- Inside Crimp Taping
(Lead Style: M*)



Unit : mm

Customer Part Number	Murata Part Number	T.C.	DC Rated Volt. (V)	Cap.	Cap. Tol.	Dimension (mm)						Dimension (LxW) Lead Style	Pack qty. (pcs)
						L	W	W1	F	T	H/H0		
	RDER72A334K1M1H03A	X7R	100	0.33μF	±10%	4.5	3.5	5.0	5.0	3.15	16.0	1M1	2000
	RDER72A474K1M1H03A	X7R	100	0.47μF	±10%	4.5	3.5	5.0	5.0	3.15	16.0	1M1	2000
	RDER72A684K2M1H03A	X7R	100	0.68μF	±10%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RDER72A105K2M1H03A	X7R	100	1.0μF	±10%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RDEC72A155K3M1H03A	X7S	100	1.5μF	±10%	5.5	5.0	7.5	5.0	4.0	16.0	3M1	1500
	RDEC72A225K3M1H03A	X7S	100	2.2μF	±10%	5.5	5.0	7.5	5.0	4.0	16.0	3M1	1500
	RDEC72A475K3M1H03A	X7S	100	4.7μF	±10%	5.5	5.0	7.5	5.0	4.0	16.0	3M1	2000
	RDEC72A475MWM1H03A	X7S	100	4.7μF	±20%	5.5	7.5	10.0	5.0	4.0	16.0	WM1	1500

Reference only

5.SPECIFICATIONS AND TEST METHODS																
No.	Item	Specification	Test Method													
1	Appearance	No defects or abnormalities.	Visual inspection.													
2	Dimension and Marking	Within the specified dimensions and Marking	Visual inspection, Using Caliper.													
3	Dielectric Strength	Between Terminals	The capacitor should not be damaged when voltage in Table is applied between the terminations for 1 to 5 seconds. (Charge/Discharge current \leq 50mA.) <table border="1" style="margin-left: auto; margin-right: auto;"> <tr> <th>Rated voltage</th> <th>Test voltage</th> </tr> <tr> <td>DC25V・DC50V</td> <td>250% of the rated voltage * 1</td> </tr> <tr> <td>DC100V</td> <td></td> </tr> </table>	Rated voltage	Test voltage	DC25V・DC50V	250% of the rated voltage * 1	DC100V								
Rated voltage	Test voltage															
DC25V・DC50V	250% of the rated voltage * 1															
DC100V																
The capacitor is placed in a container with metal balls of 1mm diameter so that each terminal, short-circuit, is kept approximately 2mm from the balls, and voltage in Table is impressed for 1 to 5 seconds between capacitor terminals and metal balls. (Charge/Discharge current \leq 50mA.) <table border="1" style="margin-left: auto; margin-right: auto;"> <tr> <th>Rated voltage</th> <th>Test voltage</th> </tr> <tr> <td>DC25V・DC50V</td> <td>250% of the rated voltage</td> </tr> <tr> <td>DC100V</td> <td></td> </tr> </table>	Rated voltage	Test voltage	DC25V・DC50V	250% of the rated voltage	DC100V											
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4	Insulation Resistance (I.R.)	Between Terminals	10,000MΩ or $500\text{M}\Omega \cdot \mu\text{F}$ min. * 2 (Whichever is smaller)													
5	Capacitance	Within the specified tolerance.														
6	Dissipation Factor (D.F.)	X7R : 0.025 max. X7S : 0.125 max.														
7	Capacitance Temperature Characteristics	X7R : within $\pm 15\%$ X7S : within $\pm 22\%$	The capacitance change should be measured after 5 min. at each specified temperature stage. The ranges of capacitance change compared with the 25°C value over the temperature ranges shown in the table should be within the specified ranges. <table border="1" style="margin-left: auto; margin-right: auto;"> <tr> <th>Step</th> <th>Temperature(°C)</th> </tr> <tr> <td>1</td> <td>25\pm2</td> </tr> <tr> <td>2</td> <td>-55\pm3</td> </tr> <tr> <td>3</td> <td>25\pm2</td> </tr> <tr> <td>4</td> <td>125\pm3</td> </tr> <tr> <td>5</td> <td>25\pm2</td> </tr> </table> <p>• Pretreatment Perform a heat treatment at 150+0/-10°C for one hour and then set at *room condition for 24\pm2 hours.</p>		Step	Temperature(°C)	1	25 \pm 2	2	-55 \pm 3	3	25 \pm 2	4	125 \pm 3	5	25 \pm 2
Step	Temperature(°C)															
1	25 \pm 2															
2	-55 \pm 3															
3	25 \pm 2															
4	125 \pm 3															
5	25 \pm 2															
8	Terminal Strength	Tensile Strength	Termination not to be broken or loosened 													
		Bending Strength	Termination not to be broken or loosened Each lead wire should be subjected to a force of 2.5N and then be bent 90° at the point of egress in one direction. Each wire is then returned to the original position and bent 90° in the opposite direction at the rate of one bend per 2 to 3 seconds.													
9	Vibration Resistance	Appearance	No defects or abnormalities.													
		Capacitance	Within the specified tolerance.													
		D.F.	X7R : 0.025 max. X7S : 0.125 max.													
* "room condition" Temperature : 15 to 35°C, Relative humidity : 45 to 75%, Atmosphere pressure : 86 to 106kPa Below parts are applicable in <ul style="list-style-type: none"> * 1 Rated voltage \times 200% * 2 I.R. : $50\text{ M}\Omega \cdot \mu\text{F}$ min. <table border="1" style="margin-left: auto; margin-right: auto;"> <tr> <th>Char.</th> <th>Rated Voltage</th> <th>Capacitance</th> <th>Dimensions</th> </tr> <tr> <td>C7</td> <td>2A</td> <td>475</td> <td>3</td> </tr> </table>				Char.	Rated Voltage	Capacitance	Dimensions	C7	2A	475	3					
Char.	Rated Voltage	Capacitance	Dimensions													
C7	2A	475	3													

Reference only

No.	Item	Specification	Test Method
10	Solderability of Lead	Solder is deposited on unintermittently immersed portion in axial direction covering 3/4 or more in circumferential direction of lead wires.	The terminal of capacitor is dipped into a solution of ethanol (JIS K 8101) and rosin (JIS K 5902) (25% rosin in weight proportion). Immerse in solder solution for 2±0.5 seconds. In both cases the depth of dipping is up to about 1.5 to 2mm from the terminal body. Temp. of solder : 245±5°C Lead Free Solder (Sn-3.0Ag-0.5Cu) 235±5°C H60A or H63A Eutectic Solder
11-1	Resistance to Soldering Heat (Non-Preheat)	Appearance	No defects or abnormalities.
		Capacitance Change	X7R : Within ±7.5% X7S : Within ±10%
		Dielectric Strength (Between terminals)	No defects.
11-2	Resistance to Soldering Heat (On-Preheat)	Appearance	No defects or abnormalities.
		Capacitance Change	X7R : Within ±7.5% X7S : Within ±10%
		Dielectric Strength (Between terminals)	No defects.
11-3	Resistance to Soldering Heat (soldering iron method)	Appearance	No defects or abnormalities.
		Capacitance Change	X7R : Within ±7.5% X7S : Within ±10%
		Dielectric Strength (Between terminals)	No defects.
12	Temperature Cycle	Appearance	No defects or abnormalities.
		Capacitance Change	X7R, X7S : Within±12.5%
		D.F.	X7R : 0.05 max. X7S : 0.2 max.
		I.R.	1,000MΩ or 50MΩ·µF min. (Whichever is smaller)
		Dielectric Strength (Between Terminals)	No defects or abnormalities.
13	Humidity (Steady State)	Appearance	No defects or abnormalities.
		Capacitance Change	X7R, X7S : Within ±15%
		D.F.	X7R : 0.05 max. X7S : 0.2 max.
		I.R.	1,000MΩ or 50MΩ·µF min. (Whichever is smaller)

* "room condition" Temperature : 15 to 35°C, Relative humidity : 45 to 75%, Atmosphere pressure : 86 to 106kPa

Reference only

No.	Item		Specification	Test Method
14	Humidity Load	Appearance	No defects or abnormalities.	Apply the rated voltage at $40\pm2^{\circ}\text{C}$ and relative humidity of 90 to 95% for $500+24/-0$ hours. Remove and set for 24 ± 2 hours at *room condition, then measure. (Charge/Discharge current $\leq 50\text{mA}$.) • Pretreatment Perform a heat treatment at $150+0/-10^{\circ}\text{C}$ for one hour and then set at *room condition for 24 ± 2 hours.
		Capacitance Change	X7R, X7S : Within $\pm 15\%$	
		D.F.	X7R : 0.05 max. X7S : 0.2 max.	
		I.R.	500M Ω or 25M Ω · μF min. * 3 (Whichever is smaller)	
15	High Temperature Load	Appearance	No defects or abnormalities.	Apply 150% of the rated voltage at the maximum operating temperature $\pm 3^{\circ}\text{C}$ for $1000+48/-0$ hours. Remove and set for 24 ± 2 hours at *room condition, then measure. (Charge/Discharge current $\leq 50\text{mA}$.) • Pretreatment Apply test voltage for one hour at test temperature. Remove and set at *room condition for 24 ± 2 hours.
		Capacitance Change	X7R, X7S : Within $\pm 15\%$	
		D.F.	X7R : 0.05 max. X7S : 0.2 max.	
		I.R.	1,000M Ω or 50 M Ω · μF min. * 4 (Whichever is smaller)	
16	Solvent Resistance	Appearance	No defects or abnormalities.	The capacitor should be fully immersed, unagitated, in reagent at 20 to 25°C for 30 ± 5 seconds and then remove gently. Marking on the surface of the capacitor shall immediately be visually examined. Reagent : Isopropyl alcohol
		Marking	Legible	

* "room condition" Temperature : 15 to 35°C , Relative humidity : 45 to 75%, Atmosphere pressure : 86 to 106kPa

Below parts are applicable in

* 3 I.R. : 12.5 M Ω · μF min.

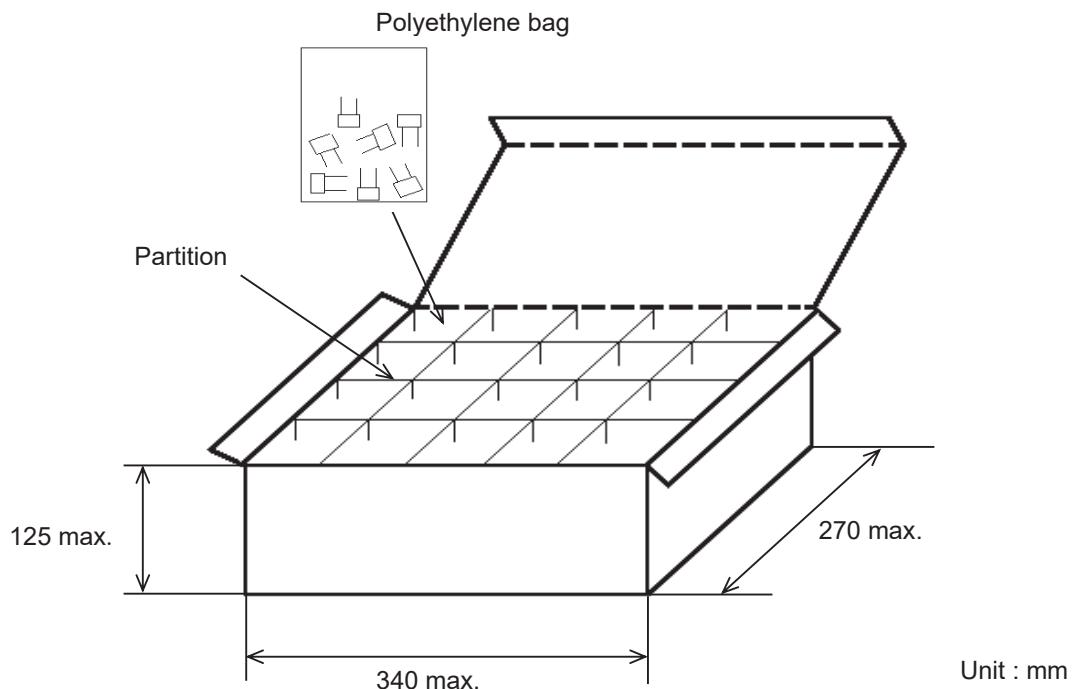
* 4 I.R. : 25 M Ω · μF min.

Char.	Rated Voltage	Capacitance	Dimensions
C7	2A	475	3

6. Packing specification

• Bulk type (Packing style code : B)

The size of packing case and packing way



The number of packing = ^{*1} Packing quantity × ^{*2} n

*1 : Please refer to [Part number list].

*2 : Standard n = 20 (bag)

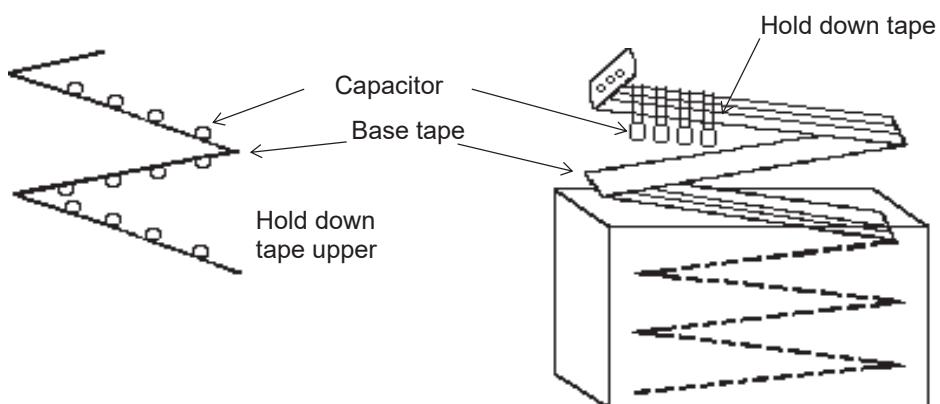
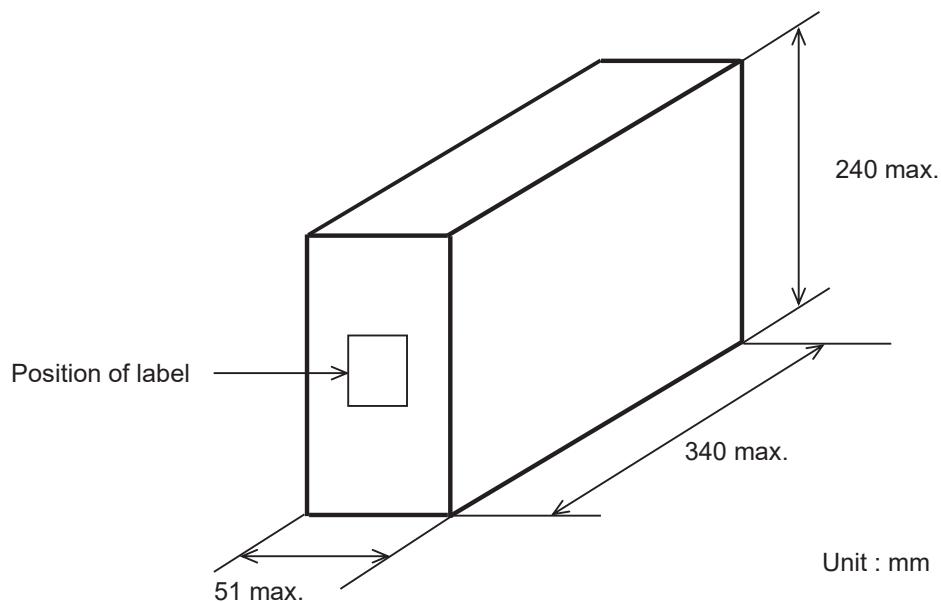
Note)

The outer package and the number of outer packing be changed by the order getting amount.

•Ammo pack taping type (Packing style code : A)

A crease is made every 25 pitches, and the tape with capacitors is packed zigzag into a case.
When body of the capacitor is piled on other body under it.

The size of packing case and packing way

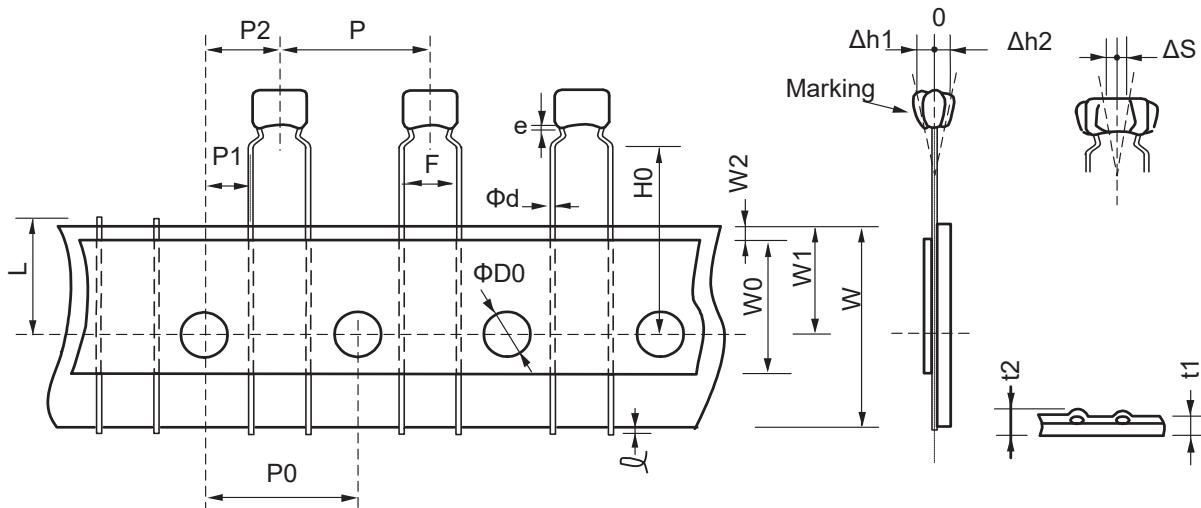


7. Taping specification

7-1. Dimension of capacitors on tape

Inside crimp taping type < Lead Style : M1 >

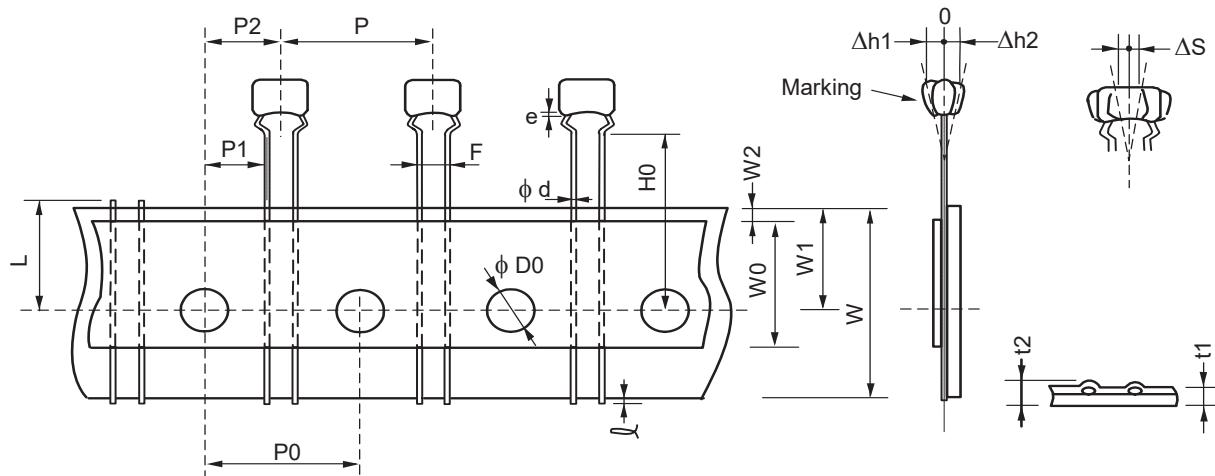
Pitch of component 12.7mm / Lead spacing 5.0mm



Unit : mm

Item	Code	Dimensions	Remarks
Pitch of component	P	12.7+/-1.0	
Pitch of sprocket hole	P0	12.7+/-0.2	
Lead spacing	F	5.0+0.6/-0.2	
Length from hole center to component center	P2	6.35+/-1.3	Deviation of progress direction
Length from hole center to lead	P1	3.85+/-0.7	
Deviation along tape, left or right defect	ΔS	0+/-2.0	They include deviation by lead bend
Carrier tape width	W	18.0+/-0.5	
Position of sprocket hole	W1	9.0+0/-0.5	Deviation of tape width direction
Lead distance between reference and bottom plane	H0	16.0+/-0.5	
Protrusion length	L	0.5 max.	
Diameter of sprocket hole	ΦD0	4.0+/-0.1	
Lead diameter	Φd	0.5+/-0.05	
Total tape thickness	t1	0.6+/-0.3	They include hold down tape thickness
Total thickness of tape and lead wire	t2	1.5 max.	
Deviation across tape	Δh1	2.0 max. (Dimension code : W)	
	Δh2	1.0 max. (except as above)	
Portion to cut in case of defect	L	11.0+0/-1.0	
Hold down tape width	W0	9.5 min.	
Hold down tape position	W2	1.5+/-1.5	
Coating extension on lead	e	Up to the end of crimp	

Outside crimp taping type < Lead Style : S1 >
Pitch of component 12.7mm / Lead spacing 2.5mm

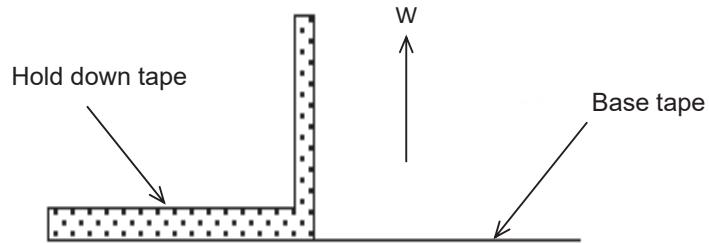


Unit : mm

Item	Code	Dimensions	Remarks
Pitch of component	P	12.7+/-1.0	
Pitch of sprocket hole	P0	12.7+/-0.2	
Lead spacing	F	2.5+0.4/-0.2	
Length from hole center to component center	P2	6.35+/-1.3	Deviation of progress direction
Length from hole center to lead	P1	5.1+/-0.7	
Deviation along tape, left or right defect	ΔS	0+/-2.0	They include deviation by lead bend
Carrier tape width	W	18.0+/-0.5	
Position of sprocket hole	W1	9.0+0/-0.5	Deviation of tape width direction
Lead distance between reference and bottom plane	H0	16.0+/-0.5	
Protrusion length	<u>l</u>	0.5 max.	
Diameter of sprocket hole	ΦD0	4.0+/-0.1	
Lead diameter	Φd	0.5+/-0.05	
Total tape thickness	t1	0.6+/-0.3	They include hold down tape thickness
Total thickness of tape and lead wire	t2	1.5 max.	
Deviation across tape	Δh1	1.0 max.	
	Δh2		
Portion to cut in case of defect	L	11.0+0/-1.0	
Hold down tape width	W0	9.5 min.	
Hold down tape position	W2	1.5+/-1.5	
Coating extension on lead	e	Up to the end of crimp	

7-2. Splicing way of tape

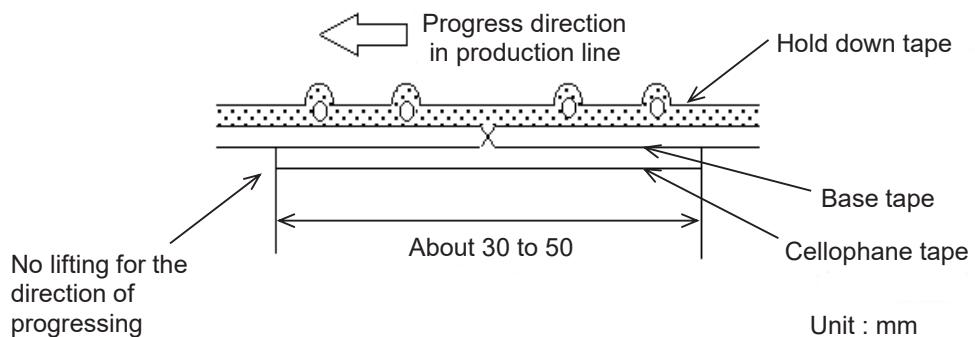
- 1) Adhesive force of tape is over 3N at test condition as below.



- 2) Splicing of tape

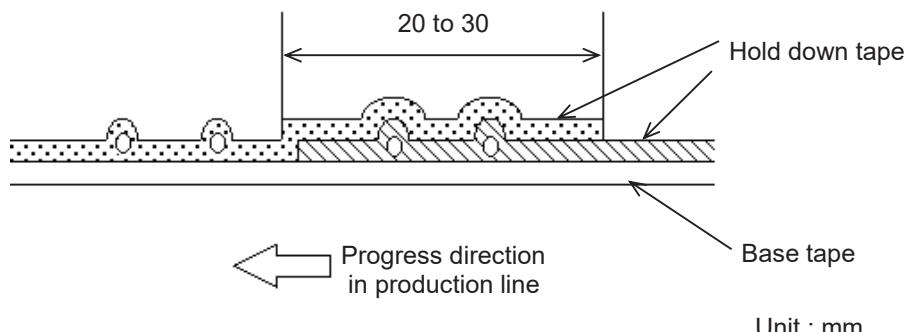
a) When base tape is spliced

- Base tape shall be spliced by cellophane tape.
(Total tape thickness shall be less than 1.05mm.)



b) When hold down tape is spliced

- Hold down tape shall be spliced with overlapping.
(Total tape thickness shall be less than 1.05mm.)



c) When both tape are spliced

- Base tape and hold down tape shall be spliced with splicing tape.